generation step is irradiated to the semiconductor device;

an operating signal application step of applying an operating signal that operates the semiconductor device to the semiconductor device;

a first measurement step of inputting the detection signal to a first electricity measurement unit; and

a second measurement step of selectively inputting the detection signal and ~~the~~a reference signal to a second electricity measurement unit.

[Claim 11]

The semiconductor device inspection method according to claim 10, wherein, in the second measurement step, the reference signal is input to the second electricity measurement unit after the detection signal is input to the second electricity measurement unit.

[Claim 12]

The semiconductor device inspection method according to claim 10, wherein, in the second measurement step, the detection signal is input to the second electricity measurement unit after the reference signal is input to the second electricity measurement unit.